

STAINLESS STEEL WALL TIES WITH INSULATION RETAINING CLIPS

SANDSTONE OUTER LEAF: MORTAR TO ENGINEERS SPEC.

CAVITY INSULATION ABOVE DPC TO BE 80MM KINGSPAN K8 Kooltherm (RIGID FOIL FACED INSULATION BOARD) WITH THERMAL CONDUCTIVITY OF 0.020W/MK.

CONTINUOUS VISQUEEN DPC CAVITY TRAY AND PROPRIETARY WEEPHOLES FORMED IN OUTER LEAF AT MAX 900MM CENTRES EQUAL SPACED.

75MM REINFORCED SAND/CONCRETE SCREED

VISQUEEN ZEDEX OPT HIGH PERFORMANCE DPC TO INNER LEAF LINKED TO DPM BELOW INSULATION DRESSED UP EDGE AND TURNED INTO BLOCKWORK

VISQUEEN ZEDEX OPT HIGH PERFORMANCE CONTINUOUS DPC TO OUTER LEAF

COMPRESSIBLE FILLER TO PERIMETER OF SCREED TO ENGINEERS DETAIL

GENERAL GROUND LEVEL AROUND BUILDING

PERISCOPIC VENTILATION BY VISQUEEN OR EQUAL

VAPOUR BARRIER TO WARM SIDE OF INSULATION

CAVITY INSULATION BELOW DPC TO BE 80MM THICKNESS OF STYROFOAM

THERMAL BLOCK BELOW SLAB IN ALL LOCATIONS WITH THERMAL CONDUCTIVITY OF 0.2W/mk OR BETTER AND COMPRESSIVE STRENGTH OF 7N/mm² OR BETTER.

BEAM AND POT FLOORING TO GROUND FLOORS WITH SAND BLINDING COURSE OVER

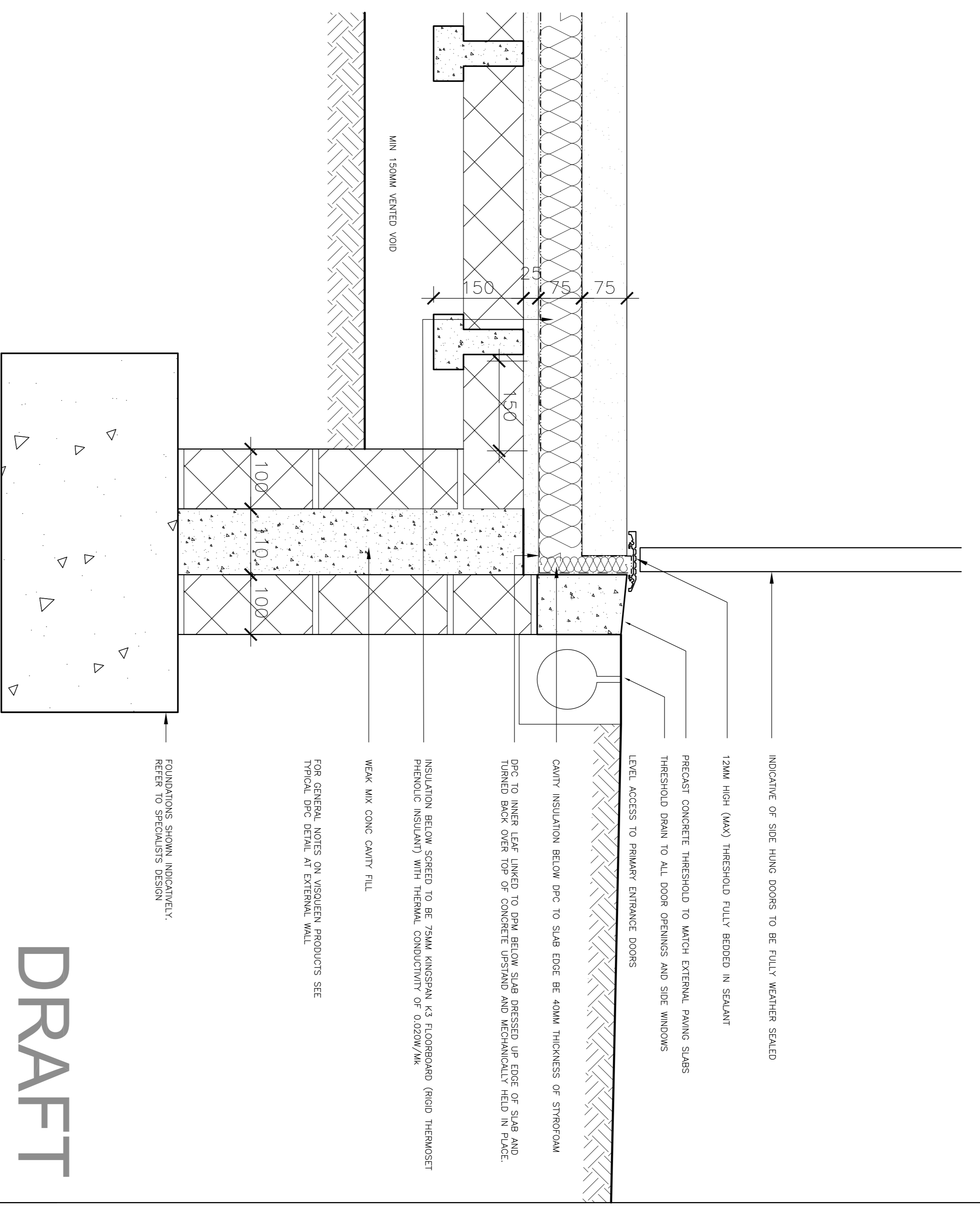
VISQUEEN EX GEOMEMBRANE GAS BARRIER LAPPED TO DPC (MIN 150MM LAP)

INSULATION BELOW SLAB TO BE 75MM KINGSPAN K3 FLOORBOARD (RIGID THERMOSET PHENOLIC INSULANT) WITH THERMAL CONDUCTIVITY OF 0.020W/MK

WEAK MIX CONC CAVITY FILL TO GROUND LEVEL

GENERAL NOTE
VISQUEEN DPM AND DPC'S ARE TO BE FULLY LAPPED AND SEALED AND TO BE INSTALLED IN ACCORDANCE WITH THE MANUFACTURERS RECOMMENDATIONS.
SYSTEM FULTS IN ACCORDANCE WITH THE MANUFACTURERS RECOMMENDATIONS.
DPM TO BE PROTECTED FROM DAMAGE AT ALL TIMES

FOUNDATIONS SHOWN INDICATIVELY.
REFER TO SPECIALISTS DESIGN



INDICATIVE OF SIDE HUNG DOORS TO BE FULLY WEATHER SEALED

12MM HIGH (MAX) THRESHOLD FULLY BEDDED IN SEALANT

PRECAST CONCRETE THRESHOLD TO MATCH EXTERNAL PAVING SLABS

THRESHOLD DRAIN TO ALL DOOR OPENINGS AND SIDE WINDOWS

LEVEL ACCESS TO PRIMARY ENTRANCE DOORS

CAVITY INSULATION BELOW DPC TO SLAB EDGE BE 40MM THICKNESS OF STYROFOAM

DPC TO INNER LEAF LINKED TO DPM BELOW SLAB DRESSED UP EDGE OF SLAB AND TURNED BACK OVER TOP OF CONCRETE UPSTAND AND MECHANICALLY HELD IN PLACE.

INSULATION BELOW SCREED TO BE 75MM KINGSPAN K3 FLOORBOARD (RIGID THERMOSET PHENOLIC INSULANT) WITH THERMAL CONDUCTIVITY OF 0.020W/MK

WEAK MIX CONC CAVITY FILL

FOR GENERAL NOTES ON VISQUEEN PRODUCTS SEE TYPICAL DPC DETAIL AT EXTERNAL WALL

FOUNDATIONS SHOWN INDICATIVELY.
REFER TO SPECIALISTS DESIGN

DRAFT

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 Architectural Design
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Title
DPC Junction Details

Project Manager/Arch/Drawn	Drawn By	Scale	Date
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